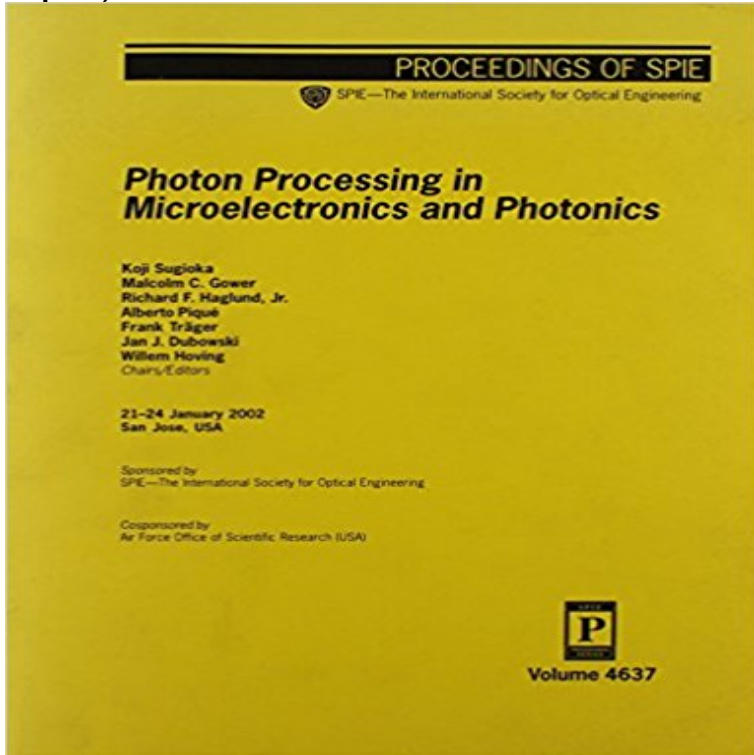


Photon Processing in Microelectronics and Photonics (Proceedings of Spie)



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